



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



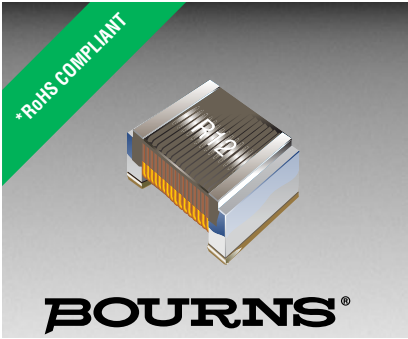
Contact us

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Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China





Features

- 1008 size
- Available in E12 series
- High Q
- High operating temperature of 125 °C
- RoHS compliant*

Applications

- Mobile phones
- Cellular phones
- CTV, VCR, HIC, FDD

CW252016 Series - High Q Chip Inductors

Electrical Specifications

Bourns® Part No.	Inductance		Q	Test Freq. (MHz)		SRF (MHz)	RDC (Ohms)		I _{rms} (mA)
	nH	Tol. %		Min.	L		Q	Min.	
CW252016-10NK	10	±10	50	50	500	4100	0.08	1000	
CW252016-12NK	12	±10	50	50	500	3300	0.09	1000	
CW252016-15NK	15	±10	50	50	500	2500	0.10	1000	
CW252016-18NK	18	±10	50	50	350	2500	0.11	1000	
CW252016-22NK	22	±10	55	50	350	2400	0.12	1000	
CW252016-27NK	27	±10	55	50	350	1600	0.13	1000	
CW252016-33NK	33	±10	60	50	350	1600	0.14	1000	
CW252016-39NK	39	±10	60	50	350	1500	0.15	1000	
CW252016-47NK	47	±10	65	50	350	1500	0.16	1000	
CW252016-56NJ	56	±5	65	50	350	1300	0.18	1000	
CW252016-68NJ	68	±5	65	50	350	1300	0.20	1000	
CW252016-82NJ	82	±5	60	50	350	1000	0.22	1000	
CW252016-R10J	100	±5	60	25.2	350	1000	0.56	650	
CW252016-R12J	120	±5	60	25.2	350	950	0.63	650	
CW252016-R15J	150	±5	45	25.2	100	850	0.70	580	
CW252016-R18J	180	±5	45	25.2	100	750	0.77	620	
CW252016-R22J	220	±5	45	25.2	100	700	0.84	500	
CW252016-R27J	270	±5	45	25.2	100	600	0.91	500	
CW252016-R33J	330	±5	45	25.2	100	570	1.05	450	
CW252016-R39J	390	±5	45	25.2	100	500	1.12	470	
CW252016-R47J	470	±5	45	25.2	100	450	1.19	470	
CW252016-R56J	560	±5	45	25.2	100	415	1.33	400	
CW252016-R68J	680	±5	45	25.2	100	375	1.55	400	
CW252016-R82J	820	±5	45	25.2	100	350	2.30	180	
CW252016-1R0J	1000	±5	35	25.2	50	290	1.75	370	
CW252016-1R2J	1200	±5	35	7.96	50	250	2.00	310	
CW252016-1R5J	1500	±5	28	7.96	50	200	2.30	330	
CW252016-1R8J	1800	±5	28	7.96	50	160	2.60	300	
CW252016-2R2J	2200	±5	28	7.96	50	160	2.80	280	
CW252016-2R7J	2700	±5	22	7.96	25	140	3.20	290	
CW252016-3R3J	3300	±5	22	7.96	25	110	3.40	290	
CW252016-3R9J	3900	±5	20	7.96	25	100	3.60	260	
CW252016-4R7J	4700	±5	20	7.96	25	50	4.00	260	

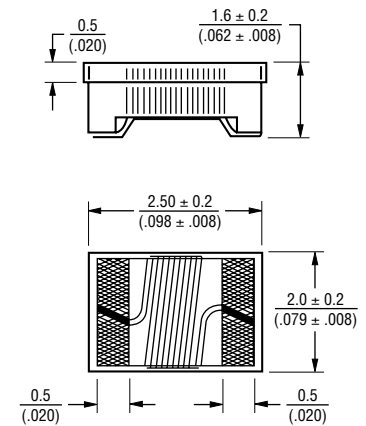
General Specifications

Temperature Rise 15 °C max. at rated current
 Operating Temperature -40 °C to +125 °C
 Storage Temperature -40 °C to +125 °C
 Reflow Soldering .. 230 °C, 50 sec. max.
 Resistance to Soldering Heat +260 °C, 5 seconds

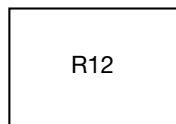
Materials

Core Material
 -10NK thru -R82J Ceramic
 -1R0J thru -4R7J Ferrite
 Wire Enameled copper (1W1E180)
 Terminal Mo/Mn+Ni+Au
 Packaging 2,000 pcs. per reel

Product Dimensions



Typical Part Marking



BOURNS®

Asia-Pacific:

Tel: +886-2 2562-4117
 Email: asiacus@bourns.com

Europe:

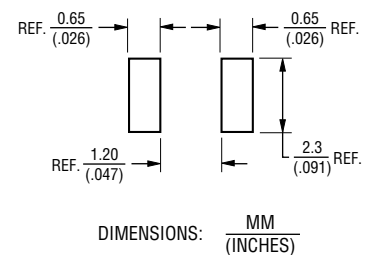
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Recommended Layout



*RoHS Directive 2002/95/EC Jan. 27, 2003 including annex and RoHS Recast 2011/65/EU June 8, 2011.

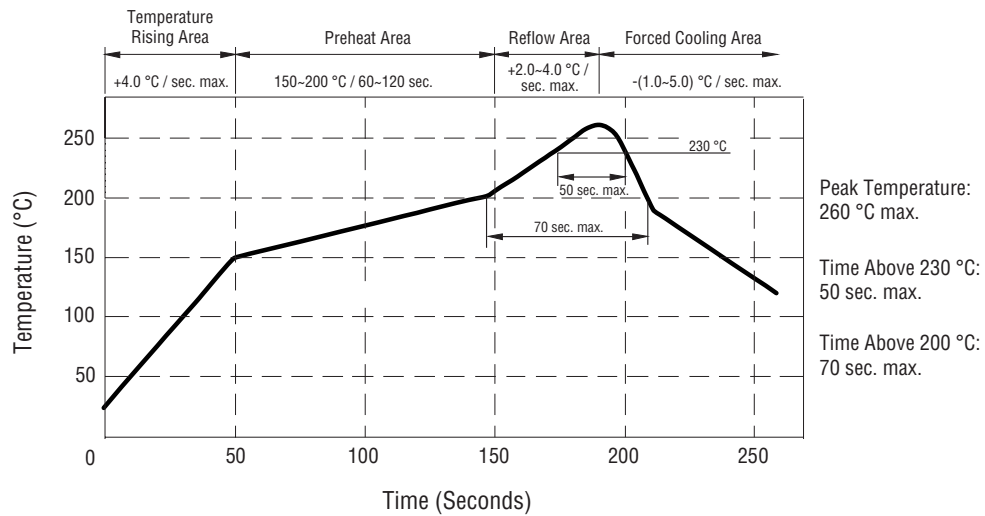
Specifications are subject to change without notice.

The device characteristics and parameters in this data sheet can and do vary in different applications and actual device performance may vary over time. Users should verify actual device performance in their specific applications.

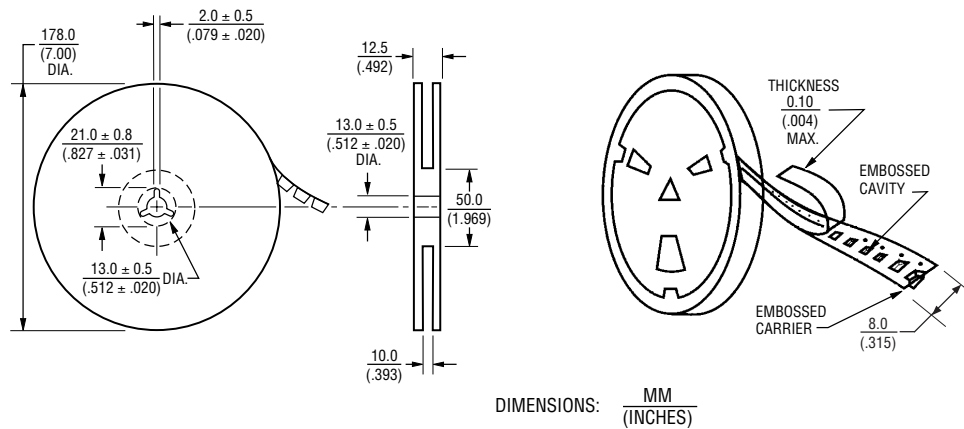
CW252016 Series - High Q Chip Inductors

BOURNS®

Soldering Profile



Packaging Specifications



REV. 01/17

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